Thermal Properties

Therocle - Bond 1600 is a thixotropic (smooth paste) thermally conductive epoxy system that provides a good match for those materials over a fairly wide temperature range. Therobond 1600 bonds readily to itself, to metals, silica, copper, glass fiber, paper, and many other materials. Ther - O- Bond 1600 is a durable, high-impact bond, with good heat transfer characteristics. It is a high performance, production potting and encapsulating application. For smaller applications, Ther - O- Bond 1600 produces a stable, rapid cure acrylic adhesive.